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Plastic encapsulated integrated circuit die packages and method of making same.

A plastic encapsulated integrated circuit package is disclosed which comprises a multilayer ground plane assembly bonded to a lead frame with an integrated circuit die bonded to the composite assembly. The multilayer ground plane assembly is first formed by bonding together a copper sheet and a thermally conductive polyimide material insulating layer to which is also bonded a layer of a b-stage epoxy resin. The ground plane assembly is then bonded to the lead frame by placing the b-stage epoxy layer of the ground plane assembly against the lead frame and heating the ground plane assembly and lead frame to a temperature of from about 120°C to just under 200°C for a time period not exceeding about 10 seconds to bond the b-stage epoxy resin to the lead frame without oxidizing it. An integrated circuit die is then attached to the composite assembly with an epoxy adhesive and the die attached assembly is then cured in a non-oxidizing atmosphere in an oven at approximately 150°C for about 90 minutes to cure the adhesive and the b-stage epoxy layer. The die is then electrically connected to the lead frame. The bonded together ground plane/lead frame/die composite assembly is then placed in a mold and encapsulated in plastic.

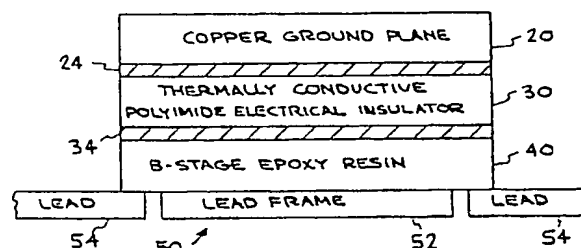


FIG. 2



DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl.5)
X	PROCEEDINGS OF THE IEEE/CHMT 1989 ELECTRONIC MANUFACTURING TECHNOLOGY SYMPOSIUM, 1989 New York, US pages 221 - 229; D.Mallik et al.: "Multi-layer molded plastic package" * page 223, paragraph 1; figures 3, 4 *	1, 2	H01L23/373 H01L23/14 H01L23/31 H01L21/56
Y	* ditto *	3, 4, 16, 19, 21	
A	* ditto *	9, 10, 12, 13, 15, 23	
Y	RESEARCH DISCLOSURE. no. 273, January 1987, New York, NY, US page 32 "Modified polyimide for Low End Packaging" * the whole document *	3, 4	
A	* ditto *	10	
Y	US-A-4783428 (M.A. KALFUS) * column 2, line 44 - column 3, line 7; figures 5-8 *	16, 19, 21	TECHNICAL FIELDS SEARCHED (Int. Cl.5)
A	* ditto *	4-6, 8, 10	H01L
A	EP-A-0064854 (ITT INDUSTRIES) * page 4, line 24 - page 5, line 26; figure 1 *	2, 3, 5, 10, 16	
A	PATENT ABSTRACTS OF JAPAN vol. 10, no. 95 (E-395)(2152) 12 April 1986, & JP-A-60 236236 (HITACHI DENSEN) 25 November 1985, * the whole document *	1, 10, 16	
A	PATENT ABSTRACTS OF JAPAN vol. 12, no. 80 (E-590)(2927) 12 March 1988, & JP-A-62 219546 (TOSHIBA CORP) 26 September 1987, * the whole document *	1, 10, 16	
The present search report has been drawn up for all claims			
Place of search BERLIN		Date of completion of the search 19 AUGUST 1991	Examiner LE MINH, I
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document I : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application F : document cited for other reasons & : member of the same patent family, corresponding document			



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London WC1V 6SE(GB)(54) **Plastic encapsulated integrated circuit die packages and method of making same.**

(57) A plastic encapsulated integrated circuit package is disclosed which comprises a multilayer ground plane assembly bonded to a lead frame with an integrated circuit die bonded to the composite assembly. The multilayer ground plane assembly is first formed by bonding together a copper sheet and a thermally conductive polyimide material insulating layer to which is also bonded a layer of a b-stage epoxy resin. The ground plane assembly is then bonded to the lead frame by placing the b-stage epoxy layer of the ground plane assembly against the lead frame and heating the ground plane assembly and lead frame to a temperature of from about 120° C to just under 200° C for a time period not exceeding about 10 seconds to bond the b-stage epoxy resin to the lead frame without oxidizing it. An integrated circuit die is then attached to the composite assembly with an epoxy adhesive and the die attached assembly is then cured in a non-oxidizing atmosphere in an oven at approximately 150° C for about 90 minutes to cure the adhesive and the b-stage epoxy layer. The die is then electrically connected to the lead frame. The bonded together ground plane/lead frame/die composite assembly is then placed in a mold and encapsulated in plastic.

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PLASTIC ENCAPSULATED INTEGRATED CIRCUIT DIE PACKAGES AND METHOD OF MAKING SAME

This invention relates to plastic encapsulated integrated circuit die packages. We will describe the formation of an improved ground plane for an integrated circuit package which is capable of also providing heat dissipation and mechanical support for the package as it is being formed.

In the packaging of integrated circuit structures, it is known to provide metal portions adjacent the integrated circuit die which electrically function as ground planes to reduce inductance, and thereby speed the performance of the device, as well as to provide a heat sink or dissipation means.

For example, Andrews U.S. Patent 4,147,889 discloses a chip carrier comprising a printed circuit board having a metal layer formed on each surface. The metal layer on one surface comprises an external heat sink of substantial surface area while the metal layer on the side to which the chip is bonded is patterned to form lead fingers and a central metal heat sink to which the chip is bonded. According to the patentees, holes may be provided through the printed circuit board which are subsequently filled with metal to provide a direct metal contact between the heat sink to which the chip is bonded and the external heat sink.

Butt U.S. Patent 4,410,927 teaches a casing for an electrical component such as an integrated circuit die with a metal base member onto which the die is bonded using an epoxy adhesive. A lead frame is also sealed and bonded to the metal base member. A metal housing member is mounted upon the base member to form an enclosed casing.

Daniels et al U.S. Patent 4,680,613 discloses a low impedance package for an integrated circuit die comprising a lead frame without a central paddle and a ground plate which forms the die attach plane and which is spaced from and parallel to the lead frame. A dielectric layer is formed between the lead frame and the ground plate.

Katagiri Japanese Patent document 59-207645 discloses a semiconductor device and lead frame wherein a heat dissipating plate is connected to a semiconductor chip through a mounting agent which is a good heat conductor. After connecting the chip to leads via wires, the chip and leads are sealed by a resin mold layer so that the surface of the heat dissipating plate is exposed.

Usually, however, it is more difficult to incorporate a metal ground plane/heat sink into a plastic-encapsulated integrated circuit package because of the difficulty of orienting and mechanically assembling together the integrated circuit die, lead frame, and ground plane/heat sink prior to the encapsulation step which will then serve to provide

the mechanical bonding together of the components comprising the package.

It would, therefore be desirable to provide a plastic-encapsulated integrated circuit package incorporating therein an electrical ground plane/thermal heat sink and a method of assembling such a structure which will provide a mechanically stable and strong structure prior to encapsulation.

We will describe a plastic encapsulated integrated circuit structure comprising a multilayer ground plane assembly bonded to a lead frame with an integrated circuit die bonded to the composite assembly.

We will describe a method for forming a plastic encapsulated integrated circuit structure comprising a ground plane assembly bonded to a lead frame and to an integrated circuit die.

These and other features of the invention will be apparent from the following description and accompanying drawings which illustrate preferred embodiments of the invention.

Brief Description of the Drawings

Figure 1 is a vertical cross-sectional view of ground plane assembly.

Figure 2 is a fragmentary vertical cross-sectional view showing the ground plane assembly bonded to a lead frame.

Figure 3 is a top view of the lead frame shown in Figure 3 with the outline of the ground plane assembly bonded thereto shown in dotted lines to permit view of the lead frame thereunder.

Figure 4 is a fragmentary vertical cross-sectional view taken along lines 4-4 of the structure of Figure 3 showing the bonding of the ground plane to a lead on the lead frame.

Figure 5 is a fragmentary vertical cross-sectional view of the ground plane assembly bonded to a lead frame with an integrated circuit die bonded to the composite assembly.

Figure 6 is a fragmentary vertical cross-sectional view of another embodiment showing the ground plane assembly of the invention bonded solely to the leads of a lead frame formed without a center die paddle.

Figure 7 is a top view of the lead frame shown in Figure 6 with the outline of the ground plane assembly bonded thereto shown in dotted lines to permit view of the lead frame thereunder.

Figure 8 is a fragmentary vertical cross-sectional view of the ground plane assembly bonded to a

lead frame as in Figures 6 and 7, but with an integrated circuit die bonded directly to the ground plane assembly.

Figure 9 is a vertical cross-section view of a plastic encapsulated integrated circuit structure. Figure 10 is a diagrammatical view representative of an automated process which could be utilized for forming an integrated circuit structure of the invention.

Detailed Description of the Invention

Referring now to Figure 1, a ground plane assembly 10 is generally indicated comprising a copper ground plane 20, an insulating layer 30, and a b-stage epoxy layer 40 bonded to one another. The representation of these layers depicted in Figure 1 will be understood to not be in scale, with the thickness of some of the layers exaggerated for illustrative purposes. Ground plane assembly 10, which will be bonded to a lead frame, as discussed below, is, in accordance with a preferred aspect of the invention, preassembled together as a unit prior to such bonding to a lead frame.

Copper ground plane 20 in assembly 10 is bonded to electrically insulating film 30 using a high temperature-resistant adhesive 24 such as, for example, CL101, a high temperature epoxy adhesive available from the Chomerics company which is capable of withstanding temperatures as high as 300°C. Bonded to the opposite surface of insulating film 30, using a second layer 34 of the same high temperature-resistant adhesive, is b-stage epoxy layer 40.

Copper ground plane 20 generally comprises copper foil or sheet stock ranging in thickness from about 1.5 to 20 mils. Preferably the thickness will range from about 5 to 10 mils to provide both the desired electrical ground plane as well as providing good heat conductivity.

Insulating layer 30 comprises a material which will electrically insulate copper ground plane 20 from either the lead frame or the integrated circuit die as will be explained below. Insulating layer 30 ranges in thickness from about 1 to about 3 mils, and preferably comprises a polyimide film such as, for example, Kapton. Most preferably, insulating layer 30, while exhibiting electrical insulation properties, will be a heat conductor. Such materials are commercially available, for example, as alumina-filled polyimide films.

For example, it has been found that a structure of the invention can provide about 11% better heat conductivity over conventionally formed structures when a conventional polyimide insulating layer is used, but from 15 to 20% improvement in heat conductivity when a heat conducting polyimide in-

sulating film is used.

The b-stage epoxy film layer 40 comprises an epoxy resin which has been partially cured or cross linked to a degree where it resembles cheese in that it is a non-sticky solid which is still flexible and capable of further curing, as well as adherence to other materials upon application of heat to assembly 10. The thickness of epoxy layer 40 generally ranges from about 1 to about 3 mils. Examples of commercially available b-stage epoxy resins which may be used in the practice of the invention include Amicon C990 epoxy resin (w/o silver flake filler) available from Emerson and Cuming, Inc., a division of W.R. Grace and Company.

Referring now to Figures 2 and 3, ground plane assembly 10 is now bonded to a conventional metal lead frame 50 which, in the embodiment shown in Figures 2-5, is provided with a center die paddle 52 and lead fingers 54 which radiate out on all four sides of lead frame 50, as can best be seen in Figure 3.

As also seen in Figure 3, the length and width of ground plane assembly 10, i.e., the area of assembly 10 in contact with lead frame 50, is larger than the length and width of center die paddle 52 so that ground plane assembly 10 is in contact with, and bonded to, the inner ends of lead frame leads 54 to thereby impart mechanical strength to the bonded together lead frame/ground plane composite assembly after the outer portions 56 of lead frame 50 are severed, as is commonly practiced in the art, to thereby electrically isolate the individual leads 54 from one another. Normally, such a severing operation is carried out after assembly and connection of the integrated circuit die to the lead frame and the encapsulation of the die and lead frame within a plastic encapsulant which provides the needed mechanical stability to permit severance of lead frame outer lead portions 56 from leads 54.

Ground plane assembly 10 is bonded to lead frame 50 by centrally positioning ground plane assembly 10 over lead frame 50 with the exposed surface of b-stage epoxy layer 40 resting on lead frame 50. Ground plane assembly 10 and lead frame 50 are then heated to a temperature of from about 120°C to just below 200°C for about 2 to about 10 seconds, preferably about 5 seconds, to soften and melt b-stage epoxy layer 40 sufficiently to cause lead frame 50 to bond to ground plane assembly 10 via b-stage epoxy layer 40. By a temperature of "just below 200°C" is meant a temperature of about 199°C.

It should be noted that it is important to the practice of this invention that the lead frame 50/ground plane assembly 10 sandwich or composite assembly not be heated (in an oxidizing atmosphere) for a temperature/time period sufficient

to oxidize the metal lead frame which is conventionally formed using copper and which is capable of rapidly oxidizing, i.e., within 15-20 seconds at temperatures exceeding 200° C.

It is not necessary to complete the curing of the b-stage epoxy resin at this time since the die 100 is first bonded either to central die frame paddle 52 of metal lead frame 50 or, if there is no central die frame paddle, directly to b-stage layer 40 using an epoxy adhesive made from the same epoxy resin and then all of the epoxy materials can be cured at the same time.

After ground plane assembly 10 and lead frame 50 have been bonded together, one or more leads 54 may be electrically and thermally bonded to copper ground plane layer 20, as shown in Figure 4, using an electrically conductive epoxy material 60 which may comprise a silver-filled epoxy material having sufficient metal filler to render the epoxy resin electrically conductive as well as thermally conductive. If desired, copper ground plane layer 20 may be provided with one or more tabs 22, as shown in figure 4, to facilitate such bonding to leads 54 on lead frame 50. These tabs may be electrically connected to leads 54 by, for example, spot welding.

As shown in Figure 5, an integrated circuit die 100 may now be physically bonded to die frame paddle 52 of the bonded composite assembly at 58 using, for example, an epoxy resin similar to that used in forming b-stage epoxy layer 40, except that the epoxy adhesive used here is preferably an electrically conductive epoxy, e.g., an epoxy filled with silver flake such as Amicon C990 conductive epoxy resin. Use of such an electrically conductive epoxy here provides a floating potential which is capacitively coupled to copper ground plane layer 20.

The b-stage epoxy layer 40 and the conductive epoxy resin used as the adhesive to bond the integrated circuit die to die paddle 52 of lead frame 50 may now be cured by heating the structure in a nitrogen or other non-oxidizing atmosphere to a temperature of from about 120° C up to not exceeding just under 200° C and maintaining the structure at this temperature for from about 30 to about 200 minutes, preferably from about 30 to about 120 minutes, usually about 90 minutes, to fully cure the epoxy resins.

After physical attachment of die 100 to lead paddle 52 of lead frame 50, the inner ends of leads 54 may then be conventionally attached (electrically connected) to the appropriate die pads on die 100 using bond wires 70 (Figure 9). This is usually accomplished with an automatic wire bonder such as, for example, a K&S 1482 gold wire bonder, available from Kulicke and Soffa Industries, Inc.

Turning now to Figures 6-8, another embodiment of the invention is illustrated wherein lead frame 50', as best seen in Figure 7, does not have a central die paddle 52. Ground plane assembly 10 is, therefore, bonded to lead frame 50' solely by bonding b-stage epoxy layer 40 directly to lead frame fingers 54.

In this embodiment, integrated circuit die 100 is then bonded directly to b-stage epoxy layer 40, as shown in Figure 8, preferably using, as an adhesive, an epoxy material which is at least chemically and mechanically compatible with the epoxy material in epoxy layer 40 of ground plane assembly 10. Most preferably, the epoxy adhesive comprises the same epoxy resin material as that used in epoxy layer 40 but in uncured form.

Figure 9 illustrates a cross-section of the final product of the embodiment of Figures 6-8 with the bonded together ground plane assembly/lead frame/die encapsulated in an epoxy novalac plastic encapsulating material 80 such as Sumitomo 6300H. In the cross-section shown in Figure 9, b-stage epoxy layer layer 40 and adhesive layers 24 and 34 have been omitted due to their small thickness relative to the thickness of the other portions of the structure. While Figure 9 shows the embodiment of Figures 6-8 in final form, it will be appreciated that Figure 9 also typifies the final form of the embodiment of Figures 2-5 except for the omission of the central die paddle on which die 100 is mounted in the first embodiment.

An integrated circuit structure of the invention, as typified by the structure of Figure 9, was tested for heat dissipation in comparison to a conventionally formed plastic-encapsulated integrated circuit structure. The prior art structure was found to have a 32.7° C average temperature rise per watt of power, when operated at a 2 watt level. The plastic-encapsulated integrated circuit structure of the invention, in contrast, had a 29.1° C rise in temperature per watt at the same power level.

Furthermore, logic-type plastic-encapsulated integrated circuit structures constructed in accordance with the invention, such as an 80286 die, were found to operate at faster speeds due to the lower inductance due to the presence of copper ground plane layer 20. For example a control run of conventionally constructed plastic encapsulated chips with no ground plane yielded only 8% 16 mHz chips, while a run constructed in accordance with the invention yielded 31% 16 mHz chips.

In either embodiment, the preassembly or formation of ground plane assembly 10 as a unit lends itself to automation of the packaging process. Figure 10 is representative of an automated process which could be used in formation of a die package using the preassembled ground plane assemblies 10 of the invention.

In Figure 10, a magazine or stack 120 of already prepared ground plane assemblies, with the copper side up, may be provided adjacent a movable belt 130 containing lead frames 50 or 50'. A robot mechanism 140 having a vacuum pickup arm 144 thereon may be moved to pick up the top most ground plane assembly 10 and centrally place it on a lead frame 50 or 50'.

The lead frame 50 or 50', with ground plane assembly 10 thereon, then may be passed through a heating station 150, e.g., through an inductance coil 154, which heats ground plane assembly 10 sufficiently to cause b-stage epoxy layer 40 thereon to bond to lead frame 50 or 50'.

The composite assembly of ground plane assembly 10 and lead frame 50 may now be passed to a die attach assembly station 160 where integrated circuit die 100 is physically bonded to the composite assembly, preferably using a conductive epoxy adhesive. The assembly then may be passed to a curing station 170 where b-stage epoxy layer 40 and the conductive epoxy resin are cured in a non-oxidizing atmosphere, such as nitrogen or argon, at a temperature of from about 120°C to not exceeding just under 200°C for a period of from about 30 to about 200 minutes. The leads on the lead frame are then electrically bonded to die pads on die 100 in a lead connection station 180.

The physically and electrically bonded together ground plane assembly/lead frame/die may then be placed in an encapsulation mold 190 and a plastic encapsulant injected into mold 190 to encapsulate the ground plane assembly/lead frame/die, resulting in the product depicted in Figure 9.

Thus, we have described an improved plastic encapsulated integrated circuit package and method of making same wherein a preassembled ground plane subassembly may be bonded to a lead frame and an integrated circuit die bonded to the composite assembly and electrically connected to the lead frame leads prior to encapsulation in plastic whereby the ground plane/lead frame/die assembly is a mechanically strong assembly which may be placed in the plastic encapsulation mold without the need for external means to retain the assembly together prior to encapsulation.

Claims

1. A plastic encapsulated integrated circuit package comprising a multilayer ground plane assembly bonded to a lead frame with an integrated circuit die bonded to the composite assembly.
2. The plastic encapsulated integrated circuit package of claim 1 wherein said multilayer ground plane assembly comprises a copper metal layer

bonded to an insulating layer.

3. The plastic encapsulated integrated circuit package of claim 2 wherein said insulating layer comprises a polyimide material.

4. The plastic encapsulated integrated circuit package of claim 2 wherein said insulating layer comprises a thermally conductive polyimide material.

5. The plastic encapsulated integrated circuit package of claim 4 wherein said thermally conductive polyimide material is bonded to a b-stage epoxy layer.

6. The plastic encapsulated integrated circuit package of claim 5 wherein said b-stage epoxy layer of said multilayer ground plane assembly is bonded to said lead frame.

7. The plastic encapsulated integrated circuit package of claim 6 wherein said b-stage epoxy layer of said multilayer ground plane assembly is bonded to said lead frame by heating said assembly and said lead frame to a temperature of from about 120°C to just under 200°C for a time period not exceeding about 10 seconds.

8. The plastic encapsulated integrated circuit package of claim 6 wherein said lead frame is formed with a central die paddle and said integrated circuit die is bonded to said central die paddle.

9. The plastic encapsulated integrated circuit package of claim 6 wherein said lead frame is formed without a central die paddle and said integrated circuit die is bonded directly to said b-stage epoxy layer of said multilayer ground plane assembly.

10. A plastic encapsulated integrated circuit package comprising:

(a) a multilayer ground plane assembly consisting essentially of:

- (i) a copper ground plane member;
- (ii) a thermally conductive polyimide insulating layer bonded to said copper ground plane member; and
- (iii) a b-stage epoxy layer bonded to to an opposite surface of said polyimide insulating layer;

(b) a lead frame bonded to said b-stage epoxy layer of said ground plane assembly to form a composite assembly; and

(c) an integrated circuit die bonded to said composite assembly and electrically connected to leads on said lead frame.

11. The plastic encapsulated integrated circuit package of claim 10 wherein said lead frame is formed with a central die paddle and said integrated circuit die is bonded to said central die paddle with an electrically conductive epoxy adhesive.

12. The plastic encapsulated integrated circuit package of claim 10 wherein said lead frame is formed without a central die paddle and said in-

egrated circuit die is bonded to said said b-stage epoxy layer of said multilayer ground plane assembly with an electrically conductive epoxy adhesive.

13. The plastic encapsulated integrated circuit package of claim 10 wherein said copper ground plane member is electrically and thermally connected to one or more leads on said lead frame.

14. The plastic encapsulated integrated circuit package of claim 13 wherein said copper ground plane member is electrically and thermally connected to one or more leads on said lead frame using a conductive epoxy resin.

15. The plastic encapsulated integrated circuit package of claim 13 wherein said copper ground plane member is provided with one or more tabs which are electrically connected to said one or more leads on said lead frame.

16. A method of making a plastic-encapsulated integrated circuit structure which comprises:

(a) forming a ground plane assembly comprising the steps of:

- (i) providing a copper ground plane member;
- (ii) bonding an electrically insulating member to said copper ground plane member; and
- (iii) bonding a b-stage epoxy member to said insulating member;

(b) bonding said ground plane assembly to a lead frame to form a composite assembly;

(c) bonding an integrated circuit die to said composite assembly; and

(d) encapsulating said bonded together ground plane assembly/lead frame/die in a plastic encapsulant.

17. The method of claim 16 wherein said step of bonding said ground plane assembly to said lead frame includes exposing said assemblies to a temperature of from about 120° C up to just under 200° C to cause said b-stage epoxy to adhere to said lead frame assembly.

18. The method of claim 16 wherein said steps of bonding said copper ground plane member to said insulating member and said insulating member to said b-stage epoxy layer further include using an adhesive capable of withstanding a temperature as high as 300° C.

19. The method of claim 16 including the further step of electrically and thermally connecting said copper ground plane member to one or more leads on said lead frame.

20. The method of claim 19 wherein said step of connecting said copper ground plane member to one or more of said leads further includes using a conductive epoxy to thermally and electrically connect said ground plane member to said one or more leads.

21. The method of claim 19 including forming one or more electrically and thermally conductive connections between one or more tabs on said copper

ground plane member and said one or more leads.

22. The method of claim 18 wherein said lead frame includes a central die paddle and said step of bonding said die to said composite assembly comprises bonding said die to said die paddle.

23. The method of claim 18 wherein said lead frame does not include a central die paddle and said step of bonding said die to said composite assembly comprises bonding said die to said b-stage epoxy layer.

24. The method of claim 23 wherein said step of bonding said die to said b-stage epoxy layer further includes using a conductive epoxy adhesive.

25. The method of claim 24 including the further step of heating said ground plane assembly/lead frame/die in a non-oxidizing atmosphere at a temperature of from about 120° C to just under 200° C for a period of from about 30 to about 200 minutes to cure said conductive epoxy adhesive and said b-stage epoxy layer.

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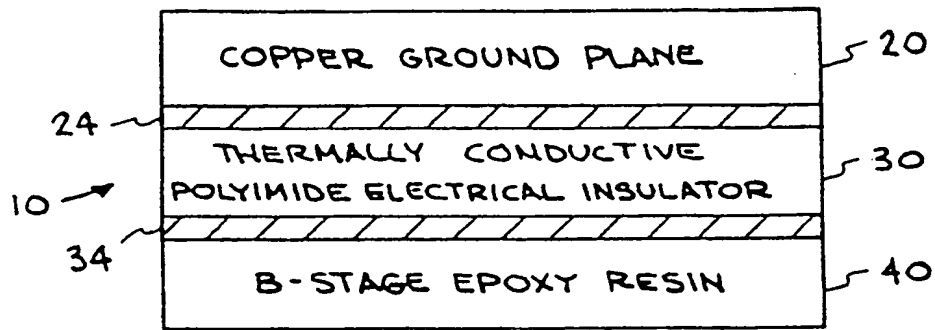


FIG. 1

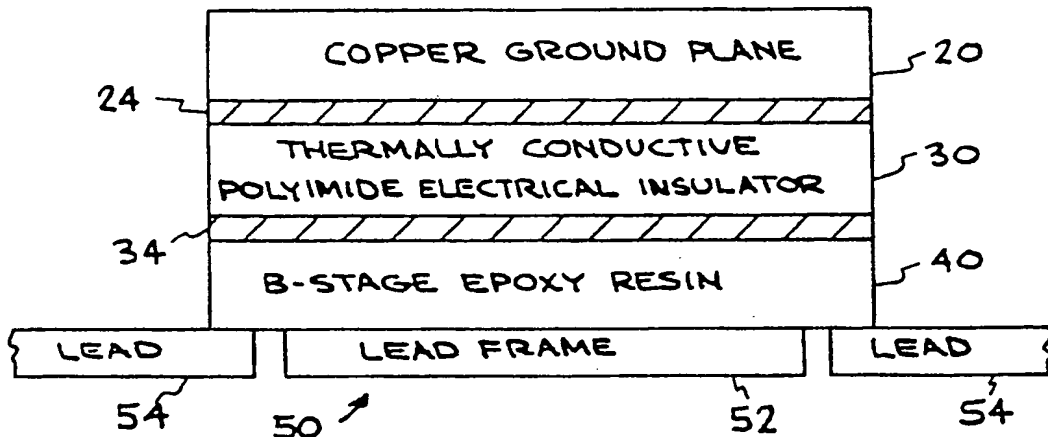


FIG. 2

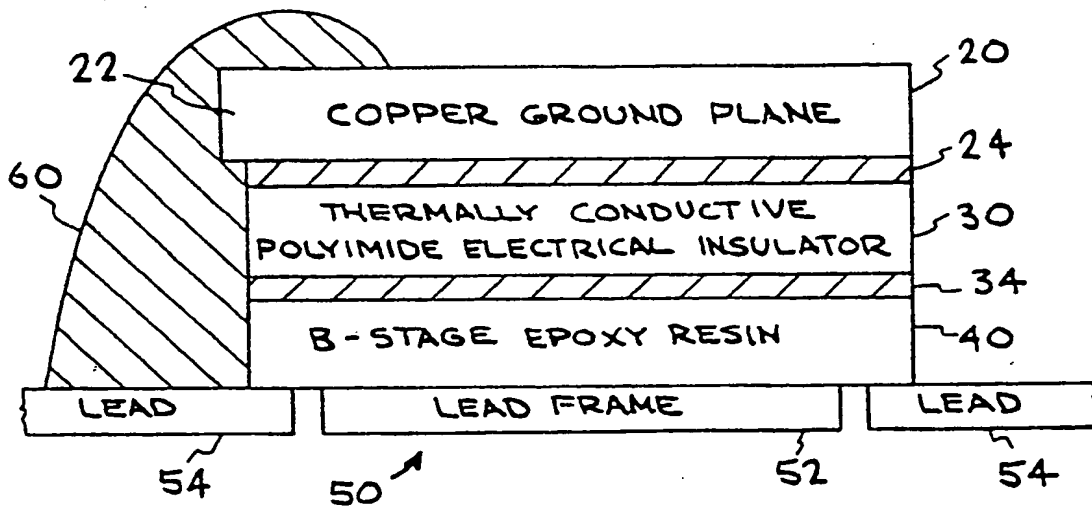


FIG. 4

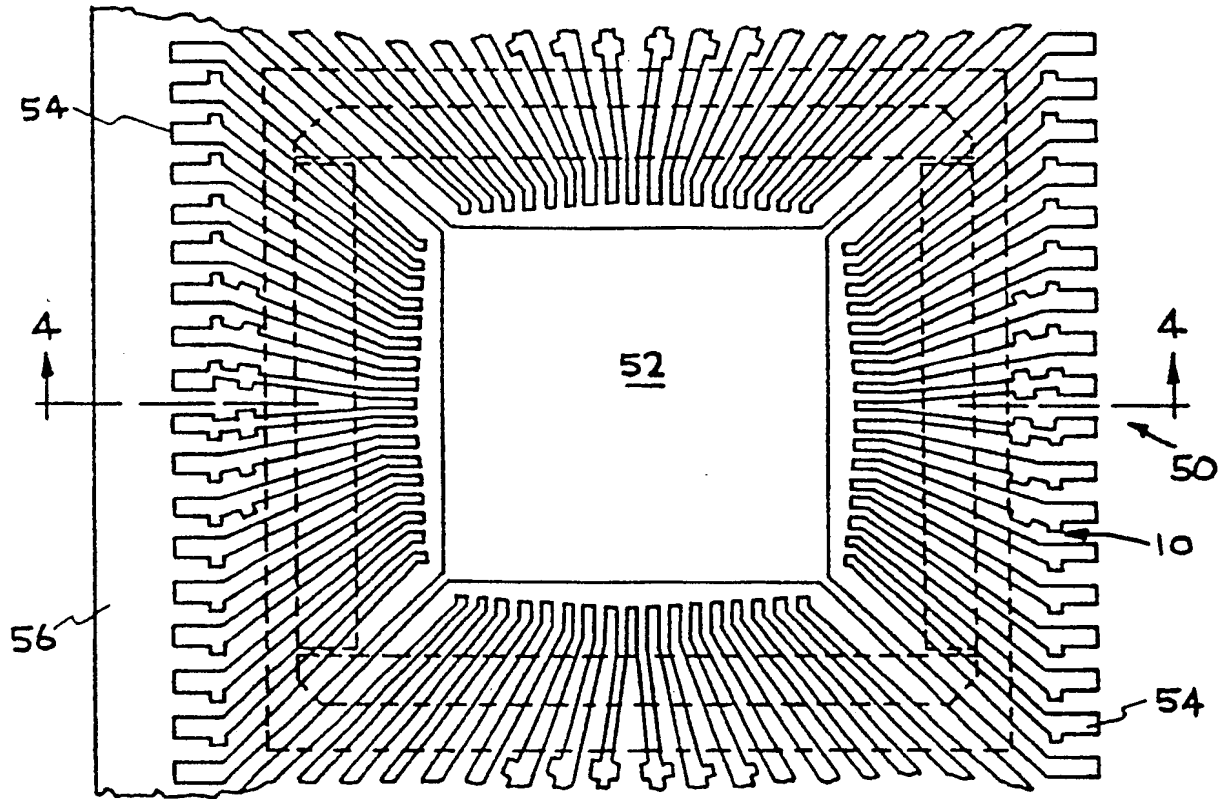


FIG. 3

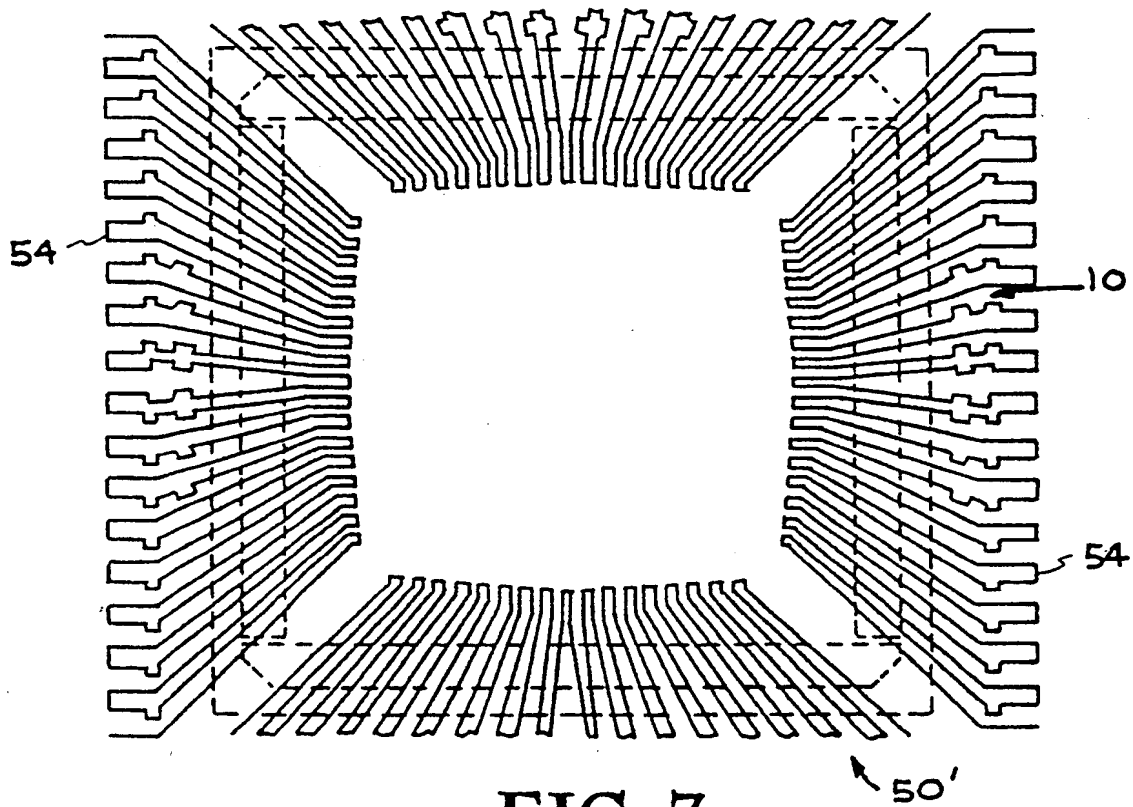


FIG. 7

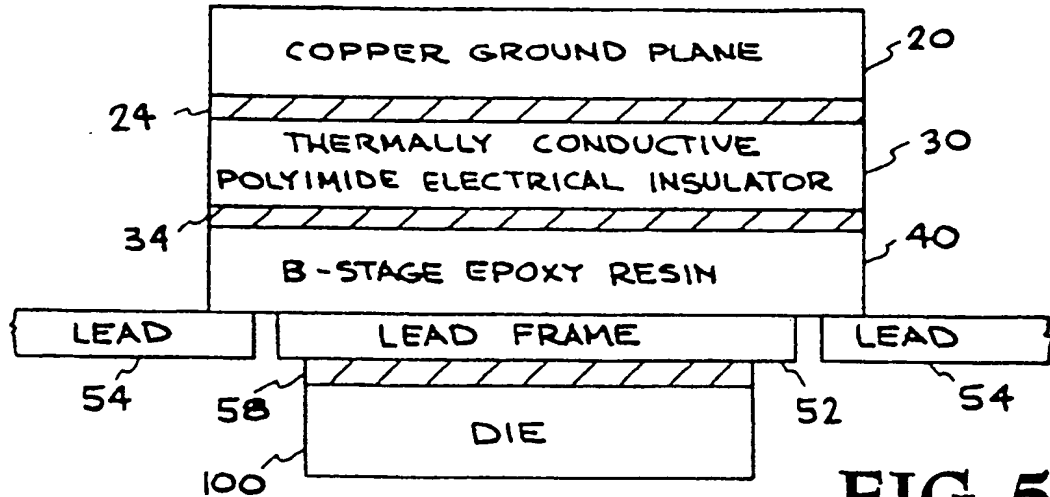


FIG. 5

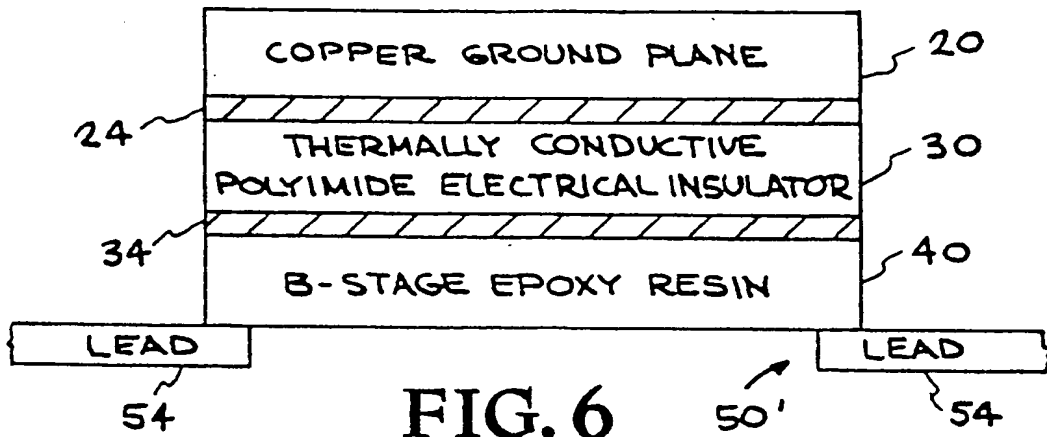


FIG. 6

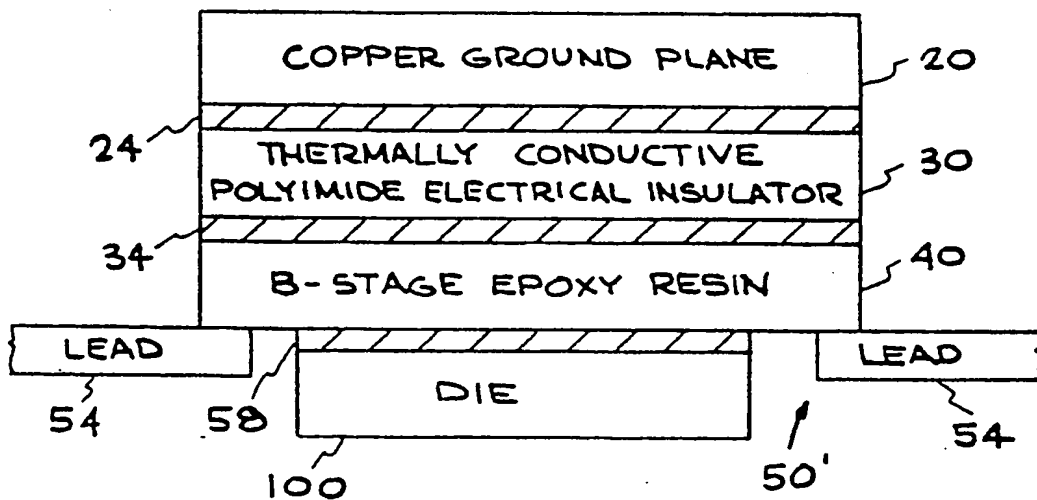


FIG. 8

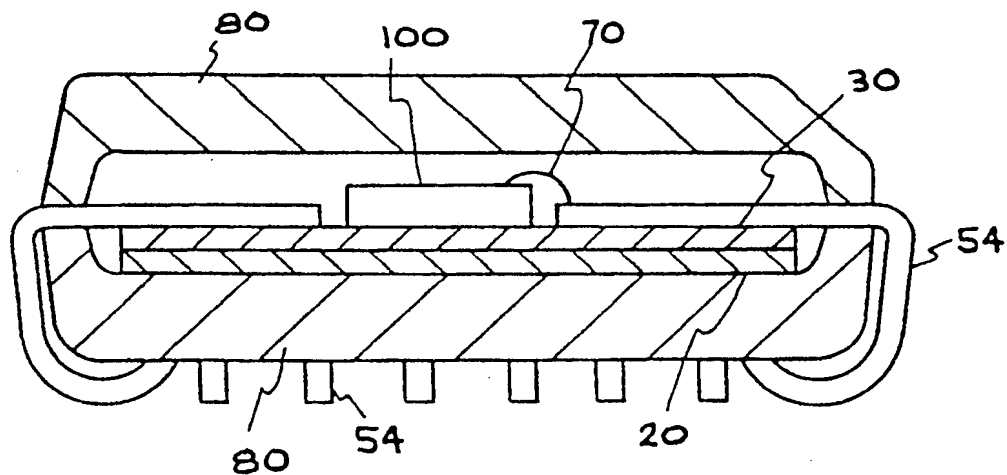


FIG. 9

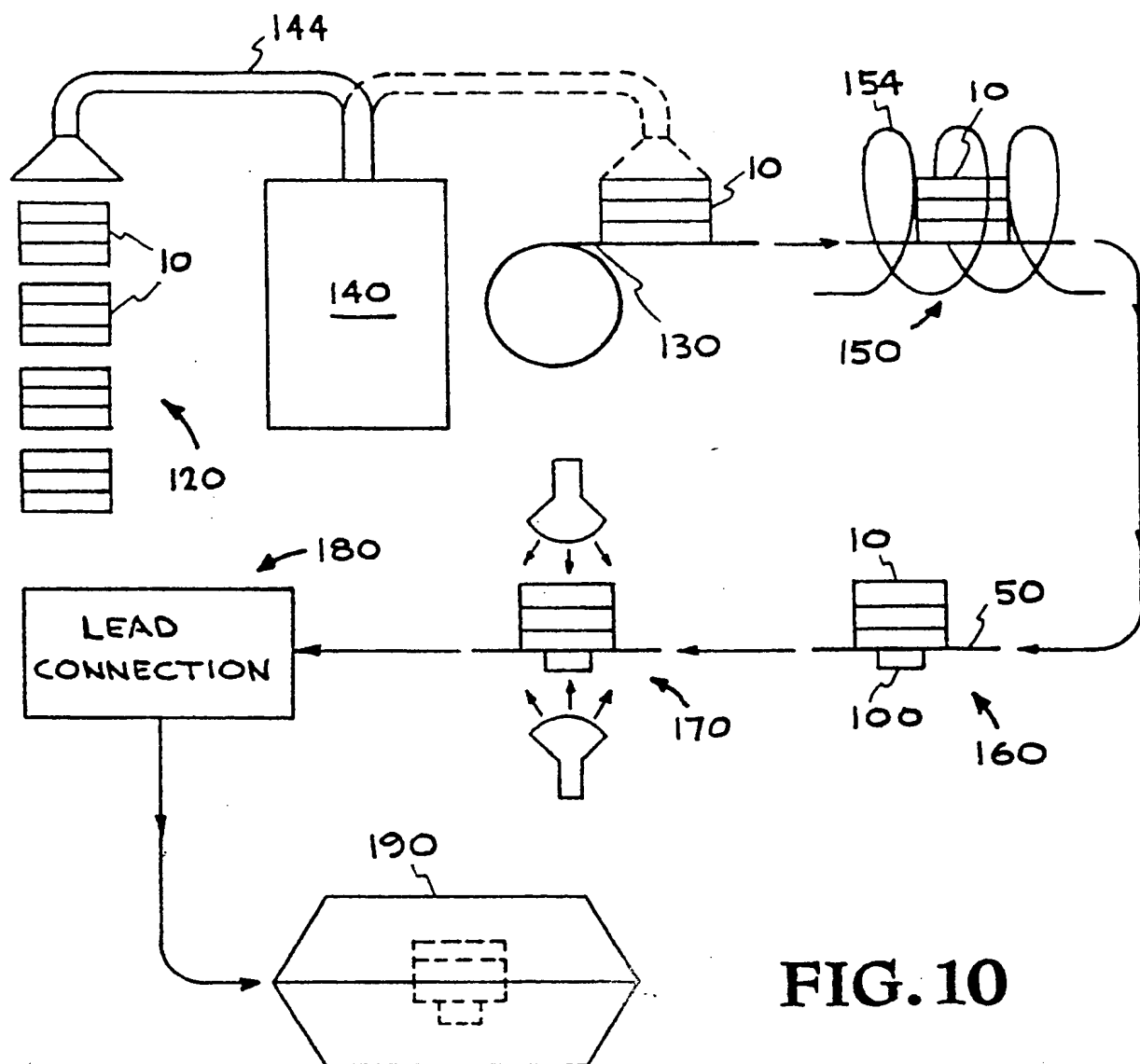


FIG. 10